

ANT + Bluetooth® Single-Chip, Dual-Mode Module

FEATURES

- Fully Qualified Bluetooth v2.1 + Enhanced Data Rate (EDR)
- ANT+ capable
- Bluetooth and ANT Smart Priority Mechanism Allows Flexible Coexistence and Simultaneous Operation
- +10 dBm Typical Tx Power with Transmit Power Control
- 93 dBm Typical Receiver Sensitivity
- Support for Bluetooth Power Saving Modes (Sniff, Hold)
- Low Power Scan Method for Page and Inquiry Scans at 1/3rd Normal Power
- Fast Algorithm for Both ACL and eSCO
- Host Controlled Interface (HCI) Supports Three and Four Wire UART Transport with Rates of up to 4Mbps
- Hardware and Software Pre-integration with TI's MSP430 Ultra Low-power Microcontroller
- Dimensions: 9 mm x 9.5 mm x 1.8 mm (CC2567-PAN1327, Integrated Antenna);
 6.5 mm x 9.5 mm x 1.8 mm (CC2567-PAN1317, Without Antenna)"
- Bluetooth, FCC, CE, IC Certified
- Operating Temperature Range: -20C° to 70°C

APPLICATIONS

- ANT+ and Bluetooth Aggregators
- · Sports and fitness devices
- · Health and wellness devices
- Ability to add ultra low-power ANT+ technology to existing Bluetooth solutions
- Connect current ANT+ applications to mobile phones and computers via Bluetooth

DESCRIPTION

The following product brief applies to Panasonic's Bluetooth module, series number: PAN1327 and PAN1317. The Bluetooth chip used is the CC2567 from Texas Instruments.

The CC2567-PAN1327/17 is the first dual-mode, ANT and Bluetooth solution in the market. This solution is a highly-integrated class 2 HCI module with increased output power capabilities offered by Panasonic using TI's CC2567 ANT+ and Bluetooth 2.1 + Enhanced Data Rate (EDR) dual-mode transceiver. Based on TI's 7th generation Bluetooth technology, the solution provides best-in-class Bluetooth RF performance of +10 dBm typical Tx power and -93 dBm typical The CC2567-PAN1327/17 receiver sensitivity. module allows customers to connect to mobile phones and computers over Bluetooth from ANT+ enabled devices, and allows customers with Bluetooth solutions to add ultra low-power ANT+ connectivity. This solution is provided as a module to help customers reduce development time, lower manufacturing costs, save board space, ease certification, and minimize RF expertise required. For evaluation and development, a platform is available that integrates the CC2567-PAN1327/17 module, Bluetooth stack, Serial Port Profile, ANT+ solution and sample source applications running on a TI host controller - MSP430.

The full specification and purchasing of the CC2567-PAN1327/17 can be found on Panasonic's website (www.panasonic.com/ti). The development kit for this solution is available for order today through the ANT + Bluetooth Health and Fitness Aggregator Kit tool folder (www.ti.com/cc2567_pan1327_antbtkit). More information on TI's wireless platform solutions can be found on TI's Wireless Connectivity Wiki (www.ti.com/connectivitywiki).

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